

## EMIF07-LCD02F3

# 7-line IPAD™, EMI filter and ESD protection for LCD and cameras

#### **Features**

- EMI symmetrical (I/O) low-pass filter
- High efficiency in EMI filtering
- Lead-free package
- Very low PCB space occupation: 1.42 mm x 1.42 mm
- Very thin package: 0.65 mm
- High efficiency in ESD suppression
- High reliability offered by monolithic integration
- High reduction of parasitic elements through integration and wafer level packaging

#### Complies with the following standards

- IEC61000-4-2 level 4 on inputs and outputs:
  - 15 kV (air discharge)
  - 8 kV (contact discharge)
- MIL STD 883E Method 3015-6 Class 3

## **Applications**

Where EMI filtering in ESD sensitive equipment is required:

- LCD for mobile phones
- Computers and printers
- Communication systems
- MCU boards

### **Description**

The EMIF07-LCD02F3 is a 7-line highly integrated device designed to suppress EMI/RFI noise in all systems subjected to electromagnetic interference. The EMIF07 Flip Chip packaging means the package size is equal to the die size.

This filter includes ESD protection circuitry, which prevents damage to the protected device when subjected to ESD surges up 15 kV.

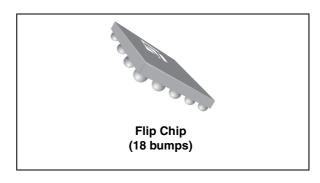


Figure 1. Pin layout (bump side)

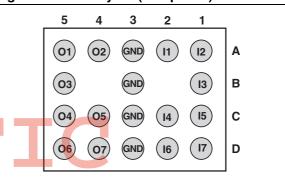
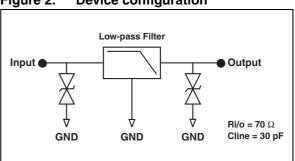


Figure 2. Device configuration



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Characteristics EMIF07-LCD02F3

### 1 Characteristics

Table 1. Absolute maximum ratings ( $T_{amb} = 25$  °C)

Symbol	Parameter and test conditions	Value	Unit
T <sub>j</sub>	Maximum junction temperature	125	°C
T <sub>op</sub>	Operating temperature range	-40 to +85	°C
T <sub>stg</sub>	Storage temperature range	-55 to 150	°C

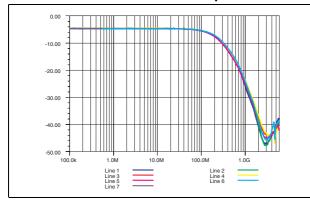
Table 2. Electrical characteristics ( $T_{amb} = 25$  °C)

Symbol	Parameters						
$V_{BR}$	Breakdown voltage			<b>'</b>			
I <sub>RM</sub>	Leakage current @ V <sub>RM</sub>			IF			
V <sub>RM</sub>	Stand-off voltage		V <sub>F</sub>				
V <sub>CL</sub>	Clamping voltage   V <sub>CL</sub> V <sub>BR</sub> V <sub>RM</sub>   V <sub>CL</sub> V <sub>BR</sub> V <sub>RM</sub>   V   V <sub>CL</sub> V <sub>RM</sub> V <sub>RM</sub> V <sub>RM</sub>   V   V <sub>CL</sub> V <sub>RM</sub> V <sub>RM</sub> V <sub>RM</sub>   V   V <sub>CL</sub> V <sub>RM</sub> V <sub>RM</sub> V <sub>RM</sub>   V   V <sub>CL</sub> V <sub>RM</sub> V <sub>RM</sub> V <sub>RM</sub> V <sub>RM</sub>   V   V <sub>CL</sub> V <sub>RM</sub>		1				
I <sub>PP</sub>	Peak pulse current						
R <sub>I/O</sub>	Series resistance between input and output						
C <sub>line</sub>	Input capacitance per line						
Symbol	Test conditions		Min	Тур	Max	Unit	
$V_{BR}$	I <sub>R</sub> = 1 mA		6	8	10	V	
I <sub>RM</sub>	V <sub>RM</sub> = 3 V			50	200	nA	
R <sub>2</sub>	Tolerance ± 20%			70		Ω	
C <sub>line</sub>	Vline = 0 V, V <sub>OSC</sub> = 30 mV, F =1 MHz				30	pF	

EMIF07-LCD02F3 Characteristics

Figure 3. S21(dB) all lines attenuation measurement and Aplac simulation

Figure 4. Analog cross talk measurement



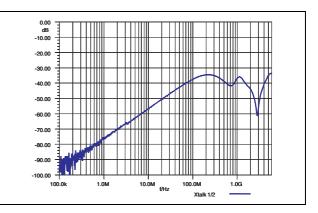


Figure 5. Voltages when IEC61000-4-2 (+15 kV air discharge) applied to input pin

Figure 6. Voltages when IEC61000-4-2 (-15 kV air discharge) applied to input pin

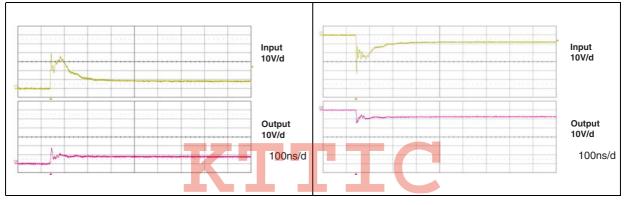
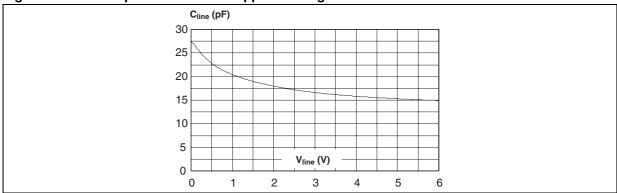


Figure 7. Line capacitance versus applied voltage



# 2 Application information

Figure 8. Aplac model

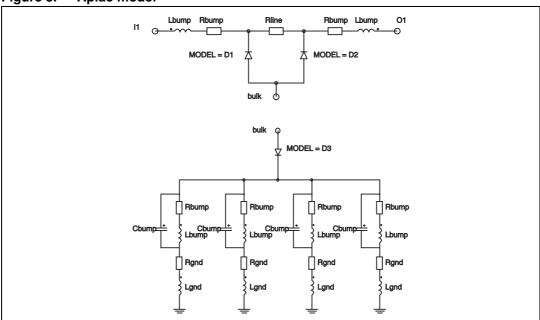
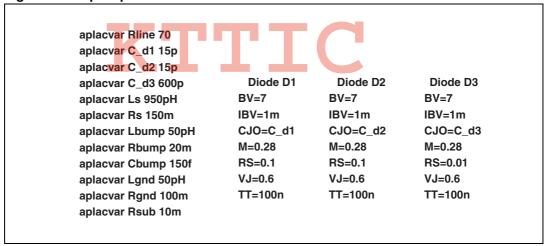


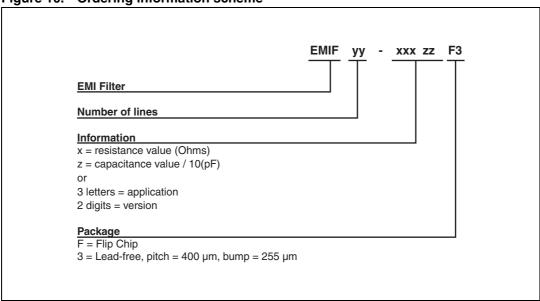
Figure 9. Aplac parameters



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## 3 Ordering information scheme

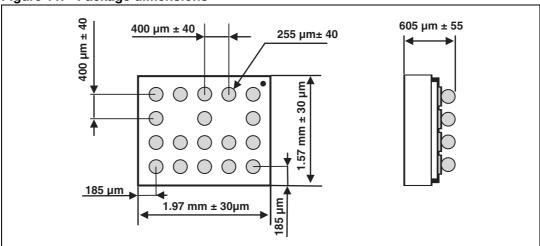
Figure 10. Ordering information scheme



# 4 Package information

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at <a href="https://www.st.com">www.st.com</a>.

Figure 11. Package dimensions



Ordering information EMIF07-LCD02F3

Figure 12. Footprint

Figure 13. Marking

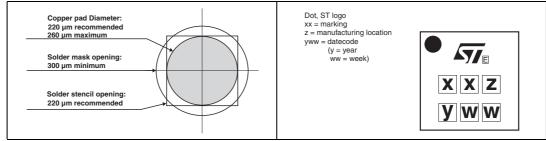
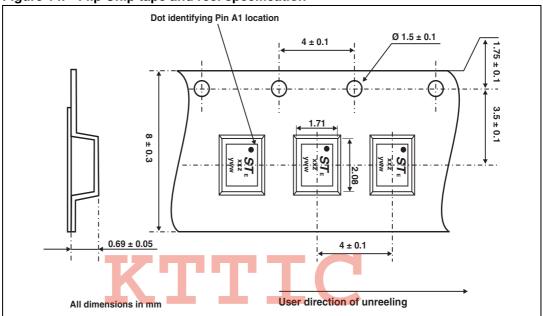


Figure 14. Flip Chip tape and reel specification



Note:

More information is available in the application notes:

AN2348: "STMicroelectronics 400 micro-metre Flip Chip: Package description and

recommendation for use"

AN1751: "EMI filters: Recommendations and measurements"

#### **Ordering information** 5

Table 3. **Ordering information** 

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF07-LCD02F3	GX	Flip Chip	3.9 mg	5000	Tape and reel 7"

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EMIF07-LCD02F3 Revision history

# 6 Revision history

Table 4. Document revision history

Date	Revision	Changes
12-Sep-2005	1	First issue.
28-Apr-2008	2	Updated ECOPACK statement. Updated Figure 10, Figure 11 and Figure 14. Reformatted to current standards.



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